

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t1963aeq-2.5#trpbf

(Engineering Calculation)

DDPAK

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TOTAL MASS (g) : 1.397064

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|---------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.003006 | 1000000 | 2151.65478516 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.852419 | 998500 | 610150.1875 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000000 | 0 | 0 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000000 | 0 | 0 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000000 | 0 | 0 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.001281 | 1500 | 916.922729492 | | |
| Lead Frame Total: | | | | 0.853700 | 1000000 | 611067.125 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.009978 | 1000000 | 7142.27587891 | | |
| | | External Plating Total: | | | | 0.009978 | 1000000 | 7142.27587891 |
| | | Inter. Plating Ni | 7440-02-0 | 0.004000 | 740740.75 | 2863.14697266 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001400 | 259259.265625 | 1002.10131836 | | |
| Internal Plating Total: | | | | 0.005400 | 1000000 | 3865.24829102 | | |
| Die Attach | 95Pb / 5 Sn | Silver (Ag) | 7440-22-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000080 | 50000 | 57.2629356384 | | |
| | | Lead (Pb) | 7439-92-1 | 0.001512 | 950000 | 1082.26953125 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000000 | 0 | 0 | | |
| Die Attach Total: | | | | 0.001592 | 1000000 | 1139.5324707 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.053704 | 103000 | 38440.609375 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.466653 | 895000 | 334024 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.001043 | 2000 | 746.565551758 | | |
| | | Encapsulation Total: | | | | 0.521400 | 1000000 | 373211.1875 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.001988 | 1000000 | 1422.98388672 | | |
| | | | | | TOTAL MASS (g) : | 1.397064 | | |